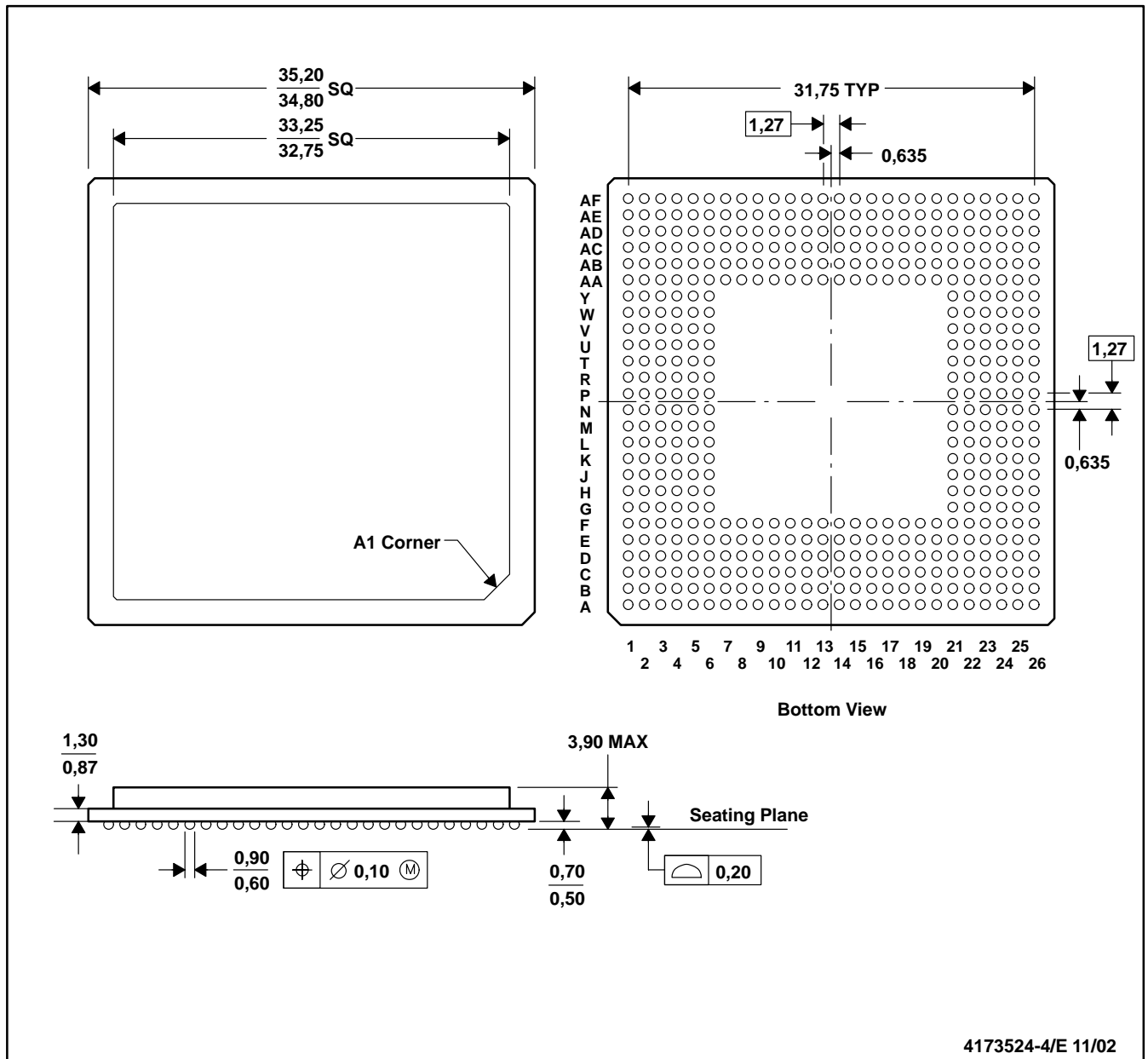


GJH (S-PBGA-N480)

PLASTIC BALL GRID ARRAY



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Thermally enhanced plastic package with heat slug (HSL)  
 D. Flip chip application only  
 E. Falls within JEDEC MO-151/BAR-2

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